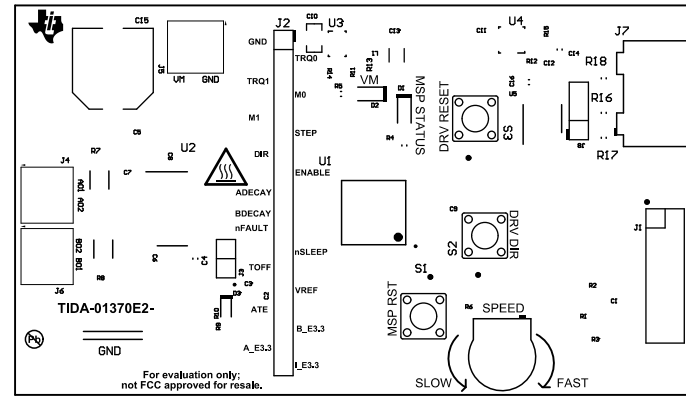
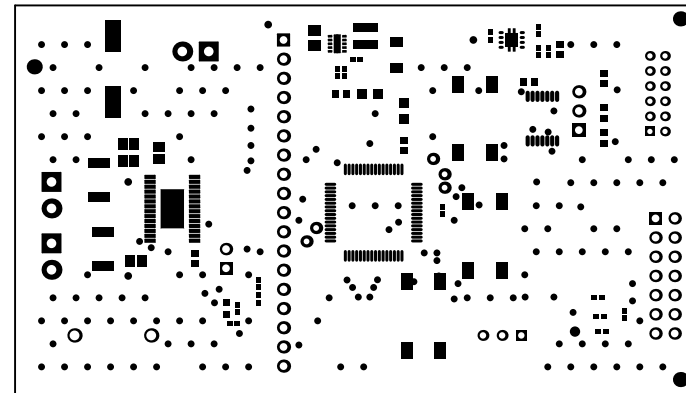


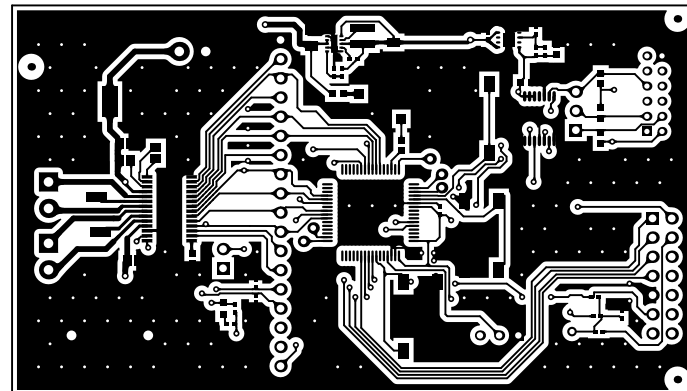
ZZ4  
 ZZ3  
 ZZ2  
 ZZ1



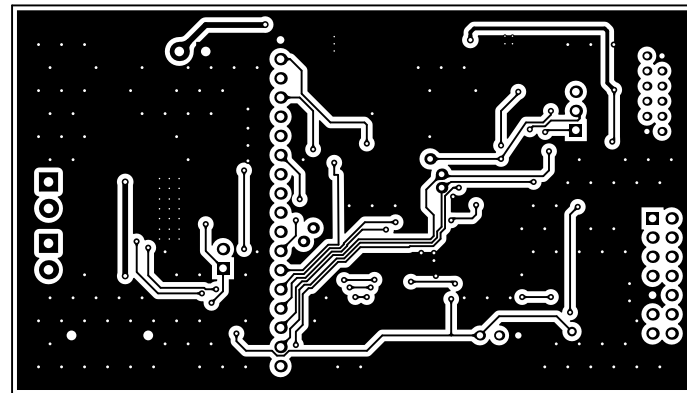
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01370	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: N/A		
PLOT NAME = Top Overlay	GENERATED : 2/27/2017 5:12:24 PM	TEXAS INSTRUMENTS	



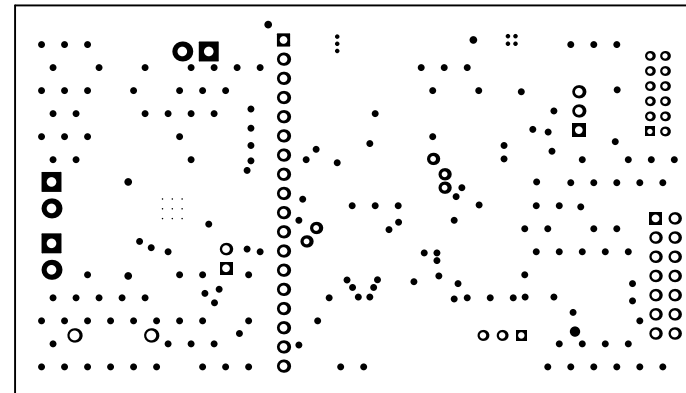
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01370	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 2/27/2017 5:12:25 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01370	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 2/27/2017 5:12:26 PM	TEXAS INSTRUMENTS	



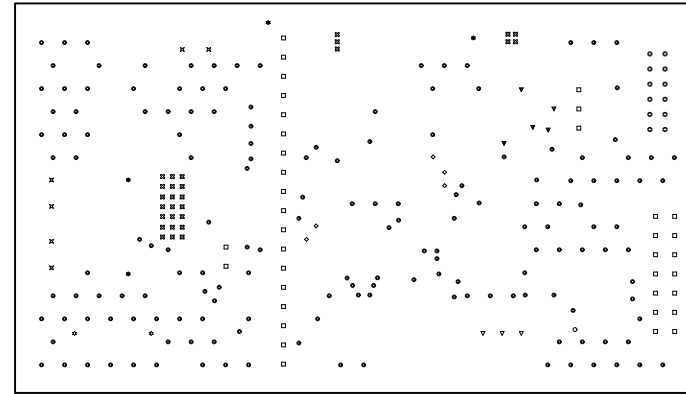
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01370	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 2/27/2017 5:12:27 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01370	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 2/27/2017 5:12:28 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01370	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: N/A		
PLOT NAME = Bottom Overlay	GENERATED : 2/27/2017 5:12:29 PM		TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⊗	28	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
⊙	165	15.00mil (0.381mm)	PTH	Round	Top Layer - Bottom Layer	
▽	5	16.00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer	
✱	4	20.00mil (0.508mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	12	27.56mil (0.700mm)	PTH	Round	Top Layer - Bottom Layer	+3.94mil/-0.00mil
○	1	28.00mil (0.711mm)	PTH	Round	Top Layer - Bottom Layer	
◇	5	30.00mil (0.762mm)	PTH	Round	Top Layer - Bottom Layer	
▽	3	33.46mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer	
□	37	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	6	50.00mil (1.270mm)	PTH	Round	Top Layer - Bottom Layer	
✱	2	51.18mil (1.300mm)	PTH	Round	Top Layer - Bottom Layer	
	268 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01370	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 2/27/2017	5:12:30 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01370	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 2/27/2017 5:12:31 PM	TEXAS INSTRUMENTS	



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